

SMT940-25

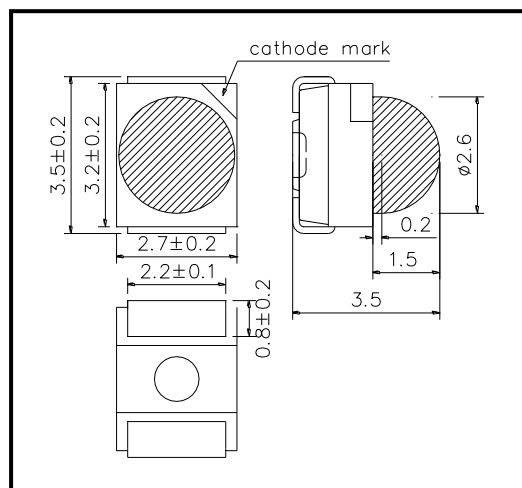
High Performance Infrared TOP LED with Lens

SMT940-25 consists of a AlGaAs LED mounted on the lead frame as TOP LED package with plastic ball lens and is 34mW typical of output power and 26mW/sr of radiant Intensity. It emits a spectral band of radiation at 940nm.

◆ Outer dimension (Unit:mm)

◆ Specifications

- | | |
|---------------------|---------------|
| 1) Product Name | TOP IR LED |
| 2) Type No. | SMT940-25 |
| 3) Chip | |
| (1) Chip Material | GaAs |
| (2) Chip Dimension | 400um*400nm |
| (3) Peak Wavelength | 940nm typ. |
| 4) Package | |
| (1) Lead Frame Die | Silver Plated |
| (2) Package Resin | PPA Resin |
| (3) Lens | Epoxy Resin |
| (4) Diameter | Φ2.6mm |



◆ Absolute Maximum Rating

Item	Symbol	Maximum Rated Value	Unit	Ambient Temperature
Power Dissipation	P _D	140	mW	T _a =25°C
Forward Current	I _F	100	mA	T _a =25°C
Pulse Forward Current	I _{FP}	1000	mA	T _a =25°C
Reverse Voltage	V _R	5	V	T _a =25°C
Junction Temperature	T _J	100	°C	
Thermal Resistance	R _{thjp}	260	K/W	
Operating Temperature	T _{OPR}	-20 ~ +80	°C	
Storage Temperature	T _{STG}	-30 ~ +80	°C	
Soldering Temperature	T _{SOL}	255	°C	

‡Pulse Forward Current condition: Duty=1% and Pulse Width=10us.

‡Soldering condition: Soldering condition must be completed within 10 seconds at 255°C

◆ Electro-Optical Characteristics [T_a=25°C]

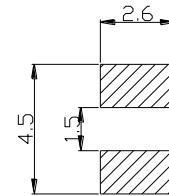
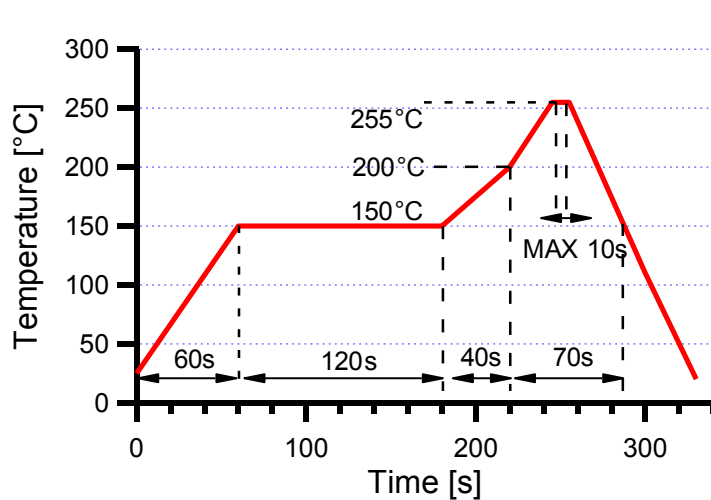
Item	Symbol	Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V _F	I _F =50mA DC		1.30	1.45	V
		I _F =100mA, t _p =20ms		1.38	1.6	
Reverse Current	I _R	V _R =5V			10	uA
Total Radiated Power	P _O	I _F =50mA DC	12.0	17.0		mW
		I _F =100mA, t _p =20ms		34.0		
Radiant Intensity	I _E	I _F =50mA DC	8	13		mW/sr
		I _F =100mA, t _p =20ms		26		
Peak Wavelength	λ _P	I _F =50mA DC	930	940	955	nm
Half Width	Δλ	I _F =50mA DC		50		nm
Viewing Half Angle	θ _{1/2}	I _F =50mA DC		±23		deg.
Rise Time	t _r	I _F =50mA DC		1000		ns
Fall Time	t _f	I _F =50mA DC		500		ns

‡Total Radiated Power is measured by Photodyne #500

‡Radiant Intensity is measured by Tektronix J-6512.

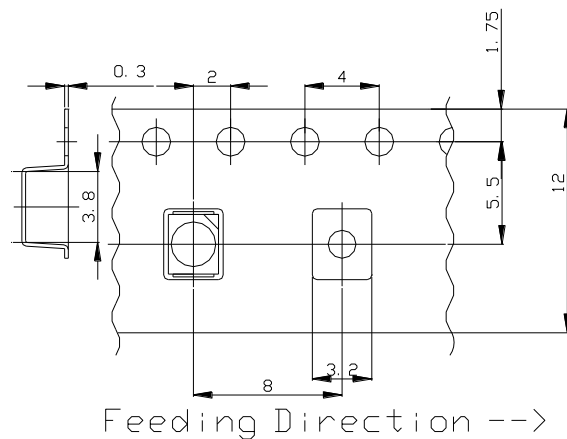
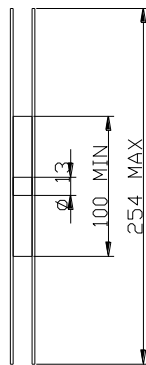
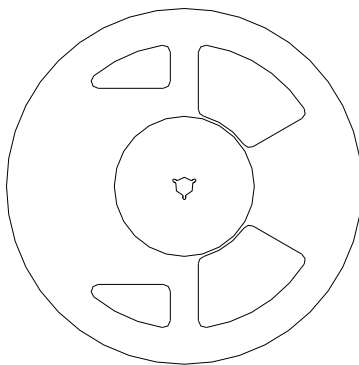
- ◆ SMD Application
IR-Reflow Soldering Profile for lead free soldering

Recommended Land Layout (Unit: mm)



Don't put stress on SMD and a circuit board after soldering.

- ◆ SMD Packing
Tape and Reel Dimensions (Unit: mm)



- ◆ Wrapping
Moisture barrier bag aluminum laminated film with a desiccant to keep out the moisture absorption during the transportation and storage.